

# 12-Ω SPDT ANALOG SWITCH 5-V/3.3-V SINGLE-CHANNEL 2:1 MULTIPLEXER/DEMULTIPLEXER

#### **FEATURES**

- Overshoot and Undershoot Voltage Protection
- Isolation in Powered-Off Mode, V<sub>+</sub> = 0
- Specified Break-Before-Make Switching
- Low ON-State Resistance (12 Ω)
- Control Inputs Are 5-V Tolerant
- Low Charge Injection
- Excellent ON-State Resistance Matching
- Low Total Harmonic Distortion (THD)
- 1.65-V to 5.5-V Single-Supply Operation
- Latch-Up Performance Exceeds 100 mA Per JESD 78, Class II
- ESD Performance Tested Per JESD 22
  - 2000-V Human-Body Model (A114-B, Class II)
  - 1000-V Charged-Device Model (C101)

#### **APPLICATIONS**

- Sample-and-Hold Circuits
- Battery-Powered Equipment
- Audio and Video Signal Routing
- Communication Circuits

#### DESCRIPTION

The TS5A63157 is a single-pole, double-throw (SPDT) analog switch designed to operate from 1.65 V to 5.5 V. This device can handle both digital and analog signals. Signals up to  $V_{+}$  (peak) can be transmitted in either direction.

TI has integrated overshoot and undershoot protection circuitry. The TS5A63157 senses overshoot and undershoot events at the I/Os and responds by preventing voltage differentials from developing and turning the switch on.

#### SOT-23 OR SC-70 PACKAGE YEP OR YZP PACKAGE (TOP VIEW) (BOTTOM VIEW) NO T 6 IN COM GND 2 5 $V_{+}$ GND (5) $V_{+}$ NC 3 COM 4

#### SUMMARY OF CHARACTERISTICS $V_{+} = 5 \text{ V}, T_{A} = 25^{\circ}\text{C}$

Configuration	Single 2:1 Multiplexer/ Demultiplexer (1 x SPDT)				
Number of channels	1				
ON-state resistance (ron)	12 Ω				
ON-state resistance match (Δr <sub>on</sub> )	0.15 Ω				
ON-state resistance flatness (r <sub>on(flat)</sub> )	6 Ω				
Turn-on/turn-off time (t <sub>ON</sub> /t <sub>OFF</sub> )	5.7 ns/3.8 ns				
Break-before-make time (t <sub>BBM</sub> )	0.5 ns				
Charge injection (Q <sub>C</sub> )	7 pC				
Bandwidth (BW)	250 MHz				
OFF isolation (O <sub>ISO</sub> )	-57 dB at 10 MHz				
Crosstalk (X <sub>TALK</sub> )	-54 dB at 10 MHz				
Total harmonic distortion (THD)	0.01%				
Leakage current (I <sub>NO(OFF)</sub> /I <sub>NC(OFF)</sub> )	±1 μA				
Power-supply current (I+)	10 μΑ				
Undershoot protection	-2 V				
Overshoot protection	V <sub>+</sub> + 2 V				
Package options	6-pin SOT-23, SC-70, and DSBGA				

#### **FUNCTION TABLE**

IN	NC TO COM, COM TO NC	NO TO COM, COM TO NO
L	ON	OFF
Н	OFF	ON

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#### ORDERING INFORMATION(1)

T <sub>A</sub>	PACKAGE <sup>(2)</sup>		PACKAGE <sup>(2)</sup> ORDERABLE PART NUMBER		ORDERABLE PART NUMBER	TOP-SIDE MARKING <sup>(3)</sup>
−40°C to 85°C	NanoStar™ - WCSP (DSBGA) 0.23-mm Large Bump - YEP	Tape and reel	TS5A63157YEPR (4)	PREVIEW		
	NanoFree™ - WCSP (DSBGA) 0.23-mm Large Bump - YZP (Pb-free)	Tape and reel	TS5A63157YZPR (4)	PREVIEW		
	SOT (SOT-23) – DBV	Tape and reel	TS5A63157DBVR	JBE_		
	SOT (SC-70) – DCK	Tape and reel	TS5A63157DCKR	J7_		

- (1) For the most current package and ordering information, see the Package Option Addendum at the end of this document, or see the TI web site at www.ti.com.
- (2) Package drawings, thermal data, and symbolization are available at www.ti.com/packaging.
- (3) DBV/DCK: The actual top-side marking has one additional character that designates the wafer faab/assembly site. YEP/YZP: The actual top-side marking has three preceding characters to denote year, month, and sequence code, and one following character to designate the wafer fab/assembly site. Pin 1 identifier indicates solder-bump composition (1 = SnPb, = Pb-free).
- (4) Package preview

#### **PIN DESCRIPTION**

NO.	NAME	DESCRIPTION
1	NO	Normally open
2	GND	Digital ground
3	NC	Normally closed
4	COM	Common
5	V <sub>+</sub>	Power supply
6	IN	Digital control to connect COM to NO or NC



### ABSOLUTE MINIMUM AND MAXIMUM RATINGS(1)(2)

over operating free-air temperature range (unless otherwise noted)

			MIN	MAX	UNIT	
V <sub>+</sub>	Supply voltage range <sup>(3)</sup>		-0.5	6.5	V	
$V_{NO} \ V_{NC} \ V_{COM}$	Analog voltage range <sup>(3)(4)(5)</sup>		-0.5	V <sub>+</sub> + 0.5	V	
$I_{K}$	Analog port diode current	$V_{NC}$ , $V_{NO}$ , $V_{COM}$ < 0 or $V_{NO}$ , $V_{NC}$ , $V_{COM}$ > $V_{+}$	-50	50	mA	
I <sub>NO</sub> I <sub>NC</sub> I <sub>COM</sub>	On-state switch current	$V_{NC}$ , $V_{NO}$ , $V_{COM} = 0$ to $V_{+}$	-50	50	mA	
$V_{I}$	Digital input voltage range (3)(4)	-0.5	6.5	٧		
$I_{IK}$	Digital input clamp current	V <sub>1</sub> < 0	-50		mA	
$I_{+}$	Continuous current through V <sub>+</sub>		-100	100	mA	
$I_{GND}$	Continuous current through GND		-100	100	mA	
		DBV package <sup>(6)</sup>		206		
0	Dealers the week instruction	DCK package (6)		252	00/14/	
$\theta_{JA}$	Package thermal impedance	YEA/YZA package <sup>(6)</sup>		143	°C/W	
		YEP/YZP package <sup>(7)</sup>		123		
T <sub>stg</sub>	Storage temperature range		-65	150	°C	

<sup>(1)</sup> Stresses above these ratings may cause permanent damage. Exposure to absolute maximum conditions for extended periods may degrade device reliability. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those specified is not implied.

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<sup>(2)</sup> The algebraic convention, whereby the most negative value is a minimum and the most positive value is a maximum.

<sup>(3)</sup> All voltages are with respect to ground, unless otherwise specified.

<sup>(4)</sup> The input and output voltage ratings may be exceeded if the input and output clamp-current ratings are observed.

<sup>(5)</sup> This value is limited to 5.5 V maximum.

<sup>(6)</sup> The package thermal impedance is calculated in accordance with JESD 51-7.

<sup>(7)</sup> The package thermal impedance is calculated in accordance with JESD 51-5.



#### **ELECTRICAL CHARACTERISTICS FOR 5-V SUPPLY**

 $\mbox{V}_{+} = 4.5 \mbox{ V}$  to 5.5 V,  $\mbox{T}_{\mbox{\scriptsize A}} = -40\mbox{\ensuremath{^{\circ}}}\mbox{C}$  to 85\ensuremath{^{\circ}}\mbox{C} (unless otherwise noted)

PARAMETER	SYMBOL	TEST COM	NDITIONS	T <sub>A</sub>	V <sub>+</sub>	MIN TY	P MAX	UNIT
Analog Switch				· '				
Analog signal range	$V_{COM}, V_{NO}, V_{NC}$					0	V <sub>+</sub>	V
Voltage undershoot	$V_{IKU}$	$0 \ge (I_{NC}, I_{NO}, \text{ or } I_{COM}) \ge -$	50 mA		5.5 V		-2	V
Peak ON-state resistance	r <sub>peak</sub>	$0 \le (V_{NO} \text{ or } V_{NC}) \le V_+,$ $I_{COM} = -30 \text{ mA},$	Switch ON, See Figure 13	25°C Full	4.5 V	4.	6 11 13	Ω
		$V_{NO}$ or $V_{NC} = 0$ , $I_{COM} = 30 \text{ mA}$		25°C Full			4 6.5	
ON-state	r <sub>on</sub>	$V_{NO}$ or $V_{NC} = 2.4 \text{ V}$ , $I_{COM} = -30 \text{ mA}$	Switch ON,	25°C	4.5 V		4 8	Ω
resistance	GII	$V_{NO}$ or $V_{NC} = 4.5 \text{ V}$ ,	See Figure 13	Full 25°C		5	10 5 10	-
ON-state		$I_{COM} = -30 \text{ mA}$		Full 25°C		0.	12 1 0.14	
resistance match between channels	$\Delta r_{on}$	$V_{NO}$ or $V_{NC} = 3.15 \text{ V}$ , $I_{COM} = -30 \text{ mA}$ ,	Switch ON, See Figure 13	Full	4.5 V		0.15	Ω
ON-state resistance flatness	r <sub>on(flat)</sub>	$0 \le (V_{NO} \text{ or } V_{NC}) \le V_+,$ $I_{COM} = -30 \text{ mA},$	Switch ON, See Figure 13	25°C Full	4.5 V	1.	5 2 4	Ω
NC, NO	I <sub>NC(OFF)</sub> , I <sub>NO(OFF)</sub>	$V_{NC}$ or $V_{NO} = 0$ to $V_+$ , $V_{COM} = V_+$ to 0	Switch OFF, See Figure 14	25°C Full	5.5 V	0.00	1 0.03	
OFF leakage current	I <sub>NC(PWROFF)</sub> , I <sub>NOPWROFF)</sub>	$V_{NC}$ or $V_{NO} = 0$ to 5.5 V, $V_{COM} = 5.5$ V to 0,	Switch OFF, See Figure 14	25°C Full	0	0.1	5 1 5	μΑ
COM OFF leakage current	I <sub>COM(PWROFF)</sub>	V <sub>COM</sub> = 0 to 5.5 V, V <sub>NC</sub> or V <sub>NO</sub> = 5.5 V to 0,	Switch ON, See Figure 14	25°C Full	0	0.		μА
NC, NO ON leakage current	I <sub>NC(ON)</sub> , I <sub>NO(ON)</sub>	$V_{NC}$ or $V_{NO} = 0$ to $V_{+}$ , $V_{COM} = Open$ ,	Switch ON, See Figure 15	25°C Full	5.5 V	0.00	0.01	μА
COM ON leakage current	I <sub>COM(ON)</sub>	$V_{NC}$ or $V_{NO}$ = Open, $V_{COM}$ = 0 to $V_{+}$ ,	Switch ON, See Figure 15	25°C Full	5.5 V	0.00	3 0.03 0.05	μА
Digital Control	Input (IN)	•						
Input logic high	V <sub>IH</sub>			Full		V <sub>+</sub> × 0.7	5.5	V
Input logic low	$V_{IL}$			Full		0	V <sub>+</sub> × 0.3	V
Input leakage current	l <sub>IH</sub> , l <sub>IL</sub>	V <sub>I</sub> = 5.5 V or 0		25°C Full	5.5 V	0.0	5 0.1 0.02	μА



### **ELECTRICAL CHARACTERISTICS FOR 5-V SUPPLY (continued)**

 $V_{+} = 4.5 \text{ V to } 5.5 \text{ V}, T_{A} = -40 ^{\circ}\text{C} \text{ to } 85 ^{\circ}\text{C} \text{ (unless otherwise noted)}$ 

PARAMETER	SYMBOL	TEST CON	IDITIONS	T <sub>A</sub>	V <sub>+</sub>	MIN	TYP	MAX	UNIT
Dynamic									
		$V_{COM} = V_{+} \text{ or GND},$	C <sub>L</sub> = 50 pF,	25°C	5 V	2	3.4	5	
Turn-on time	t <sub>ON</sub>	$R_L = 500 \Omega$ ,	See Figure 17	Full	4.5 V to 5.5 V	2		5.5	ns
		$V_{COM} = V_{+}$ or GND,	$C_{L} = 50 \text{ pF},$	25°C	5 V	1	2.8	3.4	
Turn-off time	t <sub>OFF</sub>	$R_L = 500 \Omega$ ,	See Figure 17	Full	4.5 V to 5.5 V	1		3.8	ns
Output voltage during undershoot	V <sub>OUTU</sub>	See Figure 18				2.5	V <sub>OH</sub> - 0.3		V
Output voltage during overshoot	V <sub>OUTO</sub>	See Figure 18					V <sub>OL</sub> + 0.3	2	V
Break-before-		$V_{NC} = V_{NO} = V_{+}/2,$	C <sub>L</sub> = 50 pF,	25°C	5 V	0.5	5	12	
make time	t <sub>BBM</sub>	$N_{\text{NC}} = V_{\text{NO}} = V_{\text{F}}/2,$ $R_{\text{L}} = 50 \Omega,$	See Figure 19	Full	4.5 V to 5.5 V	0.5		14	ns
Charge injection	$Q_{\mathbb{C}}$	V <sub>GEN</sub> = 0, R <sub>GEN</sub> = 0,	$C_L = 0.1 \text{ nF},$ See Figure 23	25°C	5 V		-21		рС
NC, NO OFF capacitance	$\begin{matrix} C_{NC(OFF)}, \\ C_{NO(OFF)} \end{matrix}$	$V_{NC}$ or $V_{NO} = V_{+}$ or GND, Switch OFF,	See Figure 16	25°C	5 V		5		pF
NC, NO ON capacitance	C <sub>NC(ON)</sub> , C <sub>NO(ON)</sub>	$V_{NC}$ or $V_{NO} = V_{+}$ or GND, Switch ON,	See Figure 16	25°C	5 V		14.5		pF
COM ON capacitance	C <sub>COM(ON)</sub>	V <sub>COM</sub> = V <sub>+</sub> or GND, Switch ON,	See Figure 16	25°C	5 V		14.5		pF
Digital input capacitance	Cı	$V_I = V_+ \text{ or GND},$	See Figure 16	25°C	5 V		2.5		pF
Bandwidth	BW	$R_L = 50 \Omega$ , Switch ON,	See Figure 20	25°C	5 V		371		MHz
OFF isolation	O <sub>ISO</sub>	$R_L = 50 \Omega$ , f = 10 MHz,	Switch OFF, See Figure 21	25°C	5 V		<del>-</del> 61		dB
Crosstalk	X <sub>TALK</sub>	$R_L = 50 \Omega$ , f = 10 MHz,	Switch ON, See Figure 22	25°C	5 V		-61		dB
Total harmonic distortion	THD	$R_L = 600 \ \Omega,$ $C_L = 50 \ pF,$	f = 20 Hz to 20 kHz, See Figure 24	25°C	5 V		0.06		%
Supply				-					
Positive supply current	l <sub>+</sub>	$V_I = V_+ \text{ or GND},$	Switch ON or OFF	25°C Full	5.5 V		0.01	0.1 0.75	μΑ



#### **ELECTRICAL CHARACTERISTICS FOR 3.3-V SUPPLY**

 $V_{+} = 3 \text{ V}$  to 3.6 V,  $T_{A} = -40^{\circ}\text{C}$  to 85°C (unless otherwise noted)

PARAMETER	SYMBOL	TEST CO	NDITIONS	T <sub>A</sub>	V <sub>+</sub>	MIN	TYP	MAX	UNIT
Analog Switch									
Analog signal range	$V_{COM}, V_{NO}, V_{NC}$					0		V <sub>+</sub>	٧
Voltage undershoot	V <sub>IKU</sub>	$0 \ge (I_{NC}, I_{NO}, \text{ or } I_{COM}) \ge -\xi$	50 mA		3.6 V				٧
Peak ON-state resistance	r <sub>peak</sub>	$0 \le (V_{NO} \text{ or } V_{NC}) \le V_+,$ $I_{COM} = -24 \text{ mA},$	Switch ON, See Figure 13	25°C Full	3 V		6.4	14 18	Ω
		$V_{NO}$ or $V_{NC} = 0$ ,		25°C			4.8	8	
ON-state		$I_{COM} = 24 \text{ mA}$	Switch ON.	Full				10	
resistance	r <sub>on</sub>	$V_{NO}$ or $V_{NC} = 3 V$ ,	See Figure 13	25°C	3 V		6.3	12	Ω
		$I_{COM} = -24 \text{ mA}$		Full				15	
ON-state				25°C			0.1	0.2	
resistance match between channels	Δr <sub>on</sub>	$V_{NO}$ or $V_{NC} = 2.1 \text{ V}$ , $I_{COM} = -24 \text{ mA}$ ,	Switch ON, See Figure 13	Full	3 V			0.2	Ω
ON-state		0<()/ or)/ )<)/	Switch ON,	25°C			2.8	4	
resistance flatness	r <sub>on(flat)</sub>	$0 \le (V_{NO} \text{ or } V_{NC}) \le V_+,$ $I_{COM} = -24 \text{ mA},$	See Figure 13	Full	3 V			7	Ω
	I <sub>NC(OFF)</sub> ,	$V_{NC}$ or $V_{NO} = 0$ to $V_+$ ,	Switch OFF,	25°C	3.6 V		0	0.03	- μΑ
NC, NO OFF leakage	I <sub>NO(OFF)</sub>	$V_{COM} = V_{+}$ to 0	See Figure 14	Full	3.0 V			0.05	
current	I <sub>NC(PWROFF)</sub> ,	$V_{NC}$ or $V_{NO} = 0$ to 3.6 V,	Switch OFF,	25°C	0		0.15	0.50	
	I <sub>NOPWROFF)</sub>	$V_{COM} = 3.6 \text{ V to } 0,$	See Figure 14	Full				2	
COM		$V_{COM} = 0 \text{ to } 3.6 \text{ V},$	Switch ON,	25°C	0		0.2	0.5	
OFF leakage current	I <sub>COM(PWROFF)</sub>	$V_{NC}$ or $V_{NO} = 3.6 \text{ V to 0}$ ,	See Figure 14	Full	U			5	μΑ
NC, NO	1	$V_{NC}$ or $V_{NO} = 0$ to $V_+$ ,	Switch ON,	25°C			0.001	0.01	
ON leakage current	I <sub>NC(ON)</sub> , I <sub>NO(ON)</sub>	$V_{\text{COM}} = O_{\text{to }}V_{+},$ $V_{\text{COM}} = O_{\text{pen}},$	See Figure 15	Full	3.6 V			0.02	μΑ
COM		$V_{NC}$ or $V_{NO}$ = Open,	Switch ON,	25°C			0.003	0.03	
ON leakage current	I <sub>COM(ON)</sub>	$V_{COM} = 0 \text{ to } V_+,$	See Figure 15	Full	3.6 V			0.05	μΑ
Digital Control	Input (IN)								
Input logic high	V <sub>IH</sub>			Full		V <sub>+</sub> × 0.7		5.5	٧
Input logic low	V <sub>IL</sub>			Full		0		V <sub>+</sub> × 0.3	٧
Input leakage current	I <sub>IH</sub> , I <sub>IL</sub>	V <sub>I</sub> = 5.5 V or 0		25°C Full	3.6 V		0.005	0.01	μΑ



# **ELECTRICAL CHARACTERISTICS FOR 3.3-V SUPPLY (continued)**

 $V_{+} = 3 \text{ V}$  to 3.6 V,  $T_{A} = -40^{\circ}\text{C}$  to 85°C (unless otherwise noted)

PARAMETER	SYMBOL	TEST CON	IDITIONS	T <sub>A</sub>	V <sub>+</sub>	MIN	TYP	MAX	UNIT
Dynamic									
		$V_{COM} = V_{+} \text{ or GND},$	C <sub>L</sub> = 50 pF,	25°C	3.3 V	2	4.3	6.6	
Turn-on time	t <sub>ON</sub>	$R_L = 500 \Omega$	See Figure 17	Full	3 V to 3.6 V	2		7	ns
		$V_{COM} = V_{+}$ or GND,	C <sub>L</sub> = 50 pF,	25°C	3.3 V	1	3.3	6.3	
Turn-off time	t <sub>OFF</sub>	$R_L = 500 \Omega$ ,	See Figure 17	Full	3 V to 3.6 V	1		7	ns
Output voltage during undershoot	V <sub>OUTU</sub>	See Figure 18				2.5	V <sub>OH</sub> - 0.3		V
Output voltage during overshoot	V <sub>OUTO</sub>	See Figure 18					V <sub>OL</sub> + 0.3	2	V
Break-before-		$V_{NC} = V_{NO} = V_{+}/2,$	$C_L = 50 \text{ pF},$	25°C	3.3 V	0.5	7	17	
make time	t <sub>BBM</sub>	$R_L = 50 \Omega$ ,	See Figure 19	Full	3 V to 3.6 V	0.5		19.5	ns
Charge injection	$Q_{\mathbb{C}}$	$V_{GEN} = 0,$ $R_{GEN} = 0,$	$C_L = 0.1 \text{ nF},$ See Figure 23	25°C	3.3 V		-11.5		рC
NC, NO OFF capacitance	$\begin{array}{c} C_{NC(OFF)}, \\ C_{NO(OFF)} \end{array}$	$V_{NC}$ or $V_{NO} = V_{+}$ or GND, Switch OFF,	See Figure 16	25°C	3.3 V		5		рF
NC, NO ON capacitance	C <sub>NC(ON)</sub> , C <sub>NO(ON)</sub>	$V_{NC}$ or $V_{NO} = V_{+}$ or GND, Switch ON,	See Figure 16	25°C	3.3 V		15		pF
COM ON capacitance	C <sub>COM(ON)</sub>	V <sub>COM</sub> = V <sub>+</sub> or GND, Switch ON,	See Figure 16	25°C	3.3 V		15		pF
Digital input capacitance	Cı	$V_I = V_+ \text{ or GND},$	See Figure 16	25°C	3.3 V		2.5		pF
Bandwidth	BW	$R_L = 50 \Omega$ , Switch ON,	See Figure 20	25°C	3.3 V		370		MHz
OFF isolation	O <sub>ISO</sub>	$R_L = 50 \Omega$ , f = 10 MHz,	Switch OFF, See Figure 21	25°C	3.3 V		-60		dB
Crosstalk	X <sub>TALK</sub>	$R_L = 50 \Omega$ , f = 10 MHz,	Switch ON, See Figure 22	25°C	3.3 V		-60		dB
Total harmonic distortion	THD	$R_L = 600 \ \Omega,$ $C_L = 50 \ pF,$	f = 20 Hz to 20 kHz, See Figure 24	25°C	3.3 V		0.1		%
Supply						•			
Positive supply current	I <sub>+</sub>	$V_I = V_+ \text{ or GND},$	Switch ON or OFF	25°C Full	3.6 V		0.05	0.1 0.6	μΑ



#### **ELECTRICAL CHARACTERISTICS FOR 2.5-V SUPPLY**

 $\mbox{V}_{+} = 2.3 \mbox{ V}$  to 2.7 V,  $\mbox{T}_{\mbox{\scriptsize A}} = -40\mbox{\ensuremath{^{\circ}}}\mbox{C}$  to 85\ensuremath{^{\circ}}\mbox{C} (unless otherwise noted)

PARAMETER	SYMBOL	TEST CONDITIONS		T <sub>A</sub>	V <sub>+</sub>	MIN	TYP	MAX	UNIT
Analog Switch									
Analog signal range	$V_{COM}, V_{NO}, V_{NC}$					0		V <sub>+</sub>	V
Voltage undershoot	$V_{IKU}$	$0 \text{ mA} \ge (I_{NC}, I_{NO}, \text{ or } I_{COM})$	≥ -50 mA		2.7 V				V
Peak ON-state resistance	r <sub>peak</sub>	$0 \le (V_{NO} \text{ or } V_{NC}) \le V_+,$ $I_{COM} = -8 \text{ mA},$	Switch ON, See Figure 13	25°C Full	2.3 V		9.2	30 35	Ω
ON-state		$V_{NO}$ or $V_{NC} = 0$ , $I_{COM} = 8$ mA	Switch ON,	25°C Full			5.4	8.5 12	
resistance r <sub>on</sub>	r <sub>on</sub>	$V_{NO}$ or $V_{NC} = 2.3 \text{ V}$ , $I_{COM} = -8 \text{ mA}$	See Figure 13	25°C Full	2.3 V		8.6	15.5	Ω
ON-state		CON		25°C			0.05	0.3	
resistance match between channels	$\Delta r_{on}$	$V_{NO}$ or $V_{NC} = 1.6 \text{ V}$ , $I_{COM} = -8 \text{ mA}$ ,	Switch ON, See Figure 13	Full	2.3 V		0.00	0.5	Ω
ON-state resistance flatness	r <sub>on(flat)</sub>	$0 \le (V_{NO} \text{ or } V_{NC}) \le V_+,$ $I_{COM} = -8 \text{ mA},$	Switch ON, See Figure 13	25°C Full	2.3 V		5	9 15	Ω
NC, NO	I <sub>NC(OFF)</sub> , I <sub>NO(OFF)</sub>	$V_{NC}$ or $V_{NO} = 0$ to $V_+$ , $V_{COM} = V_+$ to 0,	Switch OFF, See Figure 14	25°C Full	2.7 V		0	0.03 0.05	
OFF leakage current	I <sub>NC(PWROFF)</sub> , I <sub>NOPWROFF)</sub>	$V_{NC}$ or $V_{NO} = 0$ to 2.7 V, $V_{COM} = 2.7$ V to 0,	Switch OFF, See Figure 14	25°C Full	0		0.15	0.50 0.75	μА
COM OFF leakage current	I <sub>COM(PWROFF)</sub>	$V_{COM} = 0 \text{ to } 2.7 \text{ V},$ $V_{NC} \text{ or } V_{NO} = 2.7 \text{ V to } 0,$	Switch ON, See Figure 14	25°C Full	0		0.2	0.5	μА
NC, NO ON leakage current	I <sub>NC(ON)</sub> , I <sub>NO(ON)</sub>	$V_{NC}$ or $V_{NO} = 0$ to $V_{+}$ , $V_{COM} = Open$ ,	Switch ON, See Figure 15	25°C Full	2.7 V	(	0.001	0.01	μА
COM ON leakage current	I <sub>COM(ON)</sub>	$V_{NC}$ or $V_{NO}$ = Open, $V_{COM}$ = 0 to $V_{+}$ ,	Switch ON, See Figure 15	25°C Full	2.7 V	(	0.003	0.03	μА
Digital Control	Input (IN)					1			
Input logic high	V <sub>IH</sub>			Full		V <sub>+</sub> × 0.75		5.5	V
Input logic low	V <sub>IL</sub>			Full		0		V <sub>+</sub> × 0.25	V
Input leakage current	I <sub>IH</sub> , I <sub>IL</sub>	V <sub>I</sub> = 5.5 V or 0		25°C Full	2.7 V	(	0.005	0.01 0.02	μА



#### **ELECTRICAL CHARACTERISTICS FOR 2.5-V SUPPLY (continued)**

 $V_{+}$  = 2.3 V to 2.7 V,  $T_{A}$  = -40°C to 85°C (unless otherwise noted)

PARAMETER	SYMBOL	TEST CON	IDITIONS	T <sub>A</sub>	V <sub>+</sub>	MIN	TYP	MAX	UNIT
Dynamic									
		$V_{COM} = V_{+}$ or GND,	C <sub>L</sub> = 50 pF,	25°C	2.5 V	3	5.8	9.6	
Turn-on time	t <sub>ON</sub>	$R_L = 500 \Omega$ ,	See Figure 17	Full	2.3 V to 2.7 V	3		12	ns
		$V_{COM} = V_{+}$ or GND,	$C_1 = 50 \text{ pF},$	25°C	2.5 V	1.5	4.5	7.3	
Turn-off time	t <sub>OFF</sub>	$R_L = 500 \Omega$	See Figure 17	Full	2.3 V to 2.7 V	1.5		7.5	ns
Output voltage during undershoot	V <sub>OUTU</sub>	See Figure 18				2.5	V <sub>OH</sub> - 0.3		V
Output voltage during overshoot	V <sub>OUTO</sub>	See Figure 18					V <sub>OL</sub> + 0.3	2	V
Break-before-		$V_{NC} = V_{NO} = V_{+}/2,$	C <sub>L</sub> = 50 pF,	25°C	2.5 V	0.5	10	25	
make time	t <sub>BBM</sub>	$R_L = 50 \Omega$ ,	See Figure 19	Full	2.3 V to 2.7 V	0.5		28.5	ns
Charge injection	$Q_{\mathbb{C}}$	$V_{GEN} = 0,$ $R_{GEN} = 0,$	$C_L = 0.1 \text{ nF},$ See Figure 23	25°C	2.5 V		-8		pC
NC, NO OFF capacitance	$\begin{matrix} C_{NC(OFF)}, \\ C_{NO(OFF)} \end{matrix}$	$V_{NC}$ or $V_{NO} = V_{+}$ or GND, Switch OFF,	See Figure 16	25°C	2.5 V		5		pF
NC, NO ON capacitance	C <sub>NC(ON)</sub> , C <sub>NO(ON)</sub>	$V_{NC}$ or $V_{NO} = V_{+}$ or GND, Switch ON,	See Figure 16	25°C	2.5 V		15		pF
COM ON capacitance	C <sub>COM(ON)</sub>	V <sub>COM</sub> = V <sub>+</sub> or GND, Switch ON,	See Figure 16	25°C	2.5 V		15		pF
Digital input capacitance	Cı	$V_I = V_+ \text{ or GND},$	See Figure 16	25°C	2.5 V		2.5		pF
Bandwidth	BW	$R_L = 50 \Omega$ , Switch ON,	See Figure 20	25°C	2.5 V		367		MHz
OFF isolation	O <sub>ISO</sub>	$R_L = 50 \Omega$ , f = 10 MHz,	Switch OFF, See Figure 21	25°C	2.5 V		-60		dB
Crosstalk	X <sub>TALK</sub>	$R_L = 50 \Omega$ , f = 10 MHz,	Switch ON, See Figure 22	25°C	2.5 V		-60		dB
Total harmonic distortion	THD	$R_L = 600 \ \Omega,$ $C_L = 50 \ pF,$	f = 20 Hz to 20 kHz, See Figure 24	25°C	2.5 V		0.15		%
Supply									
Positive supply current	I <sub>+</sub>	$V_I = V_+ \text{ or GND},$	Switch ON or OFF	25°C Full	2.7 V		0.05	0.1 0.5	nA



#### **ELECTRICAL CHARACTERISTICS FOR 1.8-V SUPPLY**

 $V_{+}$  = 1.65 V to 1.95 V,  $T_{A}$  = -40°C to 85°C (unless otherwise noted)

PARAMETER	SYMBOL	TEST CON	IDITIONS	T <sub>A</sub>	V <sub>+</sub>	MIN	TYP	MAX	UNIT
Analog Switch				"					
Analog signal range	$V_{COM}, V_{NO}, V_{NC}$					0		V <sub>+</sub>	V
Voltage undershoot	$V_{IKU}$	$0 \ge (I_{NC}, I_{NO}, \text{ or } I_{COM}) \ge -5$	0 mA		1.95 V				٧
Peak ON-state resistance	r <sub>peak</sub>	$0 \le (V_{NO} \text{ or } V_{NC}) \le V_+,$ $I_{COM} = -4 \text{ mA},$	Switch ON, See Figure 13	25°C Full	1.65 V		13.8	60 120	Ω
ON state		$V_{NO}$ or $V_{NC} = 0$ , $I_{COM} = 4$ mA	Outlete ON	25°C Full			5.9	15 15	
ON-state resistance	r <sub>on</sub>	$V_{NO}$ or $V_{NC} = 1.65 \text{ V}$ , $I_{COM} = -4 \text{ mA}$	Switch ON, See Figure 13	25°C Full	1.65 V		12.8	40	Ω
ON-state		COM - THIN		25°C			0.1	0.5	
resistance match between channels	$\Delta r_{on}$	$V_{NO}$ or $V_{NC} = 1.15 \text{ V}$ , $I_{COM} = -4 \text{ mA}$ ,	Switch ON, See Figure 13	Full	1.65 V		0.1	0.8	Ω
ON-state resistance flatness	r <sub>on(flat)</sub>	$0 \le (V_{NO} \text{ or } V_{NC}) \le V_+,$ $I_{COM} = -4 \text{ mA},$	Switch ON, See Figure 13	25°C Full	1.65 V		26.5	60 80	Ω
	I <sub>NC(OFF)</sub> ,	$V_{NC}$ or $V_{NO} = 0$ to $V_+$ ,	Switch OFF,	25°C	1.95 V		0	0.03	
NC, NO OFF leakage	I <sub>NO(OFF)</sub>	$V_{COM} = V_{+} \text{ to } 0,$	See Figure 14	Full	1.95 V			0.05	μA
current	I <sub>NC(PWROFF)</sub> , I <sub>NOPWROFF)</sub>	$V_{NC}$ or $V_{NO} = 0$ to 1.95 V, $V_{COM} = 1.95$ V to 0,	Switch OFF, See Figure 14	25°C Full	0		0.15	0.50 0.75	μΑ
COM OFF leakage current	I <sub>COM(PWROFF)</sub>	$V_{COM} = 0 \text{ to } 1.95 \text{ V},$ $V_{NC} \text{ or } V_{NO} = 1.95 \text{ V to } 0,$	Switch ON, See Figure 14	25°C Full	0		0.2	0.5	μΑ
NC, NO ON leakage current	I <sub>NC(ON)</sub> , I <sub>NO(ON)</sub>	$V_{NC}$ or $V_{NO} = 0$ to $V_+$ , $V_{COM} = Open$ ,	Switch ON, See Figure 15	25°C Full	1.95 V	0	.001	0.01	μΑ
COM		$V_{NC}$ or $V_{NO}$ = Open,	Switch ON.	25°C		0	.003	0.03	
ON leakage current	I <sub>COM(ON)</sub>	$V_{COM} = 0 \text{ to } V_+,$	See Figure 15	Full	1.95 V			0.05	μΑ
<b>Digital Control</b>	Input (IN)								
Input logic high	$V_{IH}$			Full		V <sub>+</sub> × 0.75		5.5	٧
Input logic low	$V_{IL}$			Full		0		V <sub>+</sub> × 0.25	٧
Input leakage current	I <sub>IH</sub> , I <sub>IL</sub>	V <sub>I</sub> = 5.5 V or 0		25°C Full	1.95 V	0	.005	0.01	μΑ



### **ELECTRICAL CHARACTERISTICS FOR 1.8-V SUPPLY (continued)**

 $V_{+}$  = 1.65 V to 1.95 V,  $T_{A}$  = -40°C to 85°C (unless otherwise noted)

PARAMETER	SYMBOL	TEST CON	IDITIONS	V <sub>+</sub>	MIN	TYP	MAX	UNIT	
Dynamic									
		$V_{COM} = V_{+}$ or GND,	C <sub>L</sub> = 50 pF,	25°C	1.8 V		9.5	23	
Turn-on time	t <sub>ON</sub>	$R_L = 500 \Omega$ ,	See Figure 17	Full	1.65 V to 1.95 V			24	ns
		$V_{COM} = V_{+}$ or GND,	C <sub>L</sub> = 50 pF,	25°C	1.8 V		5.9	10	
Turn-off time	t <sub>OFF</sub>	$R_L = 500 \Omega,$	See Figure 17	Full	1.65 V to 1.95 V			12	ns
Output voltage during undershoot	V <sub>OUTU</sub>	See Figure 18				2.5	V <sub>OH</sub> - 0.3		V
Output voltage during overshoot	V <sub>OUTO</sub>	See Figure 18					V <sub>OL</sub> + 0.3	2	V
Break-before-		V - V - V /2	C <sub>L</sub> = 50 pF,	25°C	1.8 V	0.5	18	50	
make time	t <sub>BBM</sub>	$V_{NC} = V_{NO} = V_{+}/2,$ $R_{L} = 50 \Omega,$	See Figure 19	Full	1.65 V to 1.95 V	0.5		55	ns
Charge injection	$Q_{\mathbb{C}}$	V <sub>GEN</sub> = 0, R <sub>GEN</sub> = 0,	$C_L = 0.1 \text{ nF},$ See Figure 23	25°C	1.8 V		<b>-</b> 5		рС
NC, NO OFF capacitance	$\begin{array}{c} C_{NC(OFF)}, \\ C_{NO(OFF)} \end{array}$	$V_{NC}$ or $V_{NO} = V_{+}$ or GND, Switch OFF,	See Figure 16	25°C	1.8 V		5.5		pF
NC, NO ON capacitance	C <sub>NC(ON)</sub> , C <sub>NO(ON)</sub>	$V_{NC}$ or $V_{NO} = V_{+}$ or GND, Switch ON,	See Figure 16	25°C	1.8 V		15.5		pF
COM ON capacitance	C <sub>COM(ON)</sub>	V <sub>COM</sub> = V <sub>+</sub> or GND, Switch ON,	See Figure 16	25°C	1.8 V		15.5		pF
Digital input capacitance	Cı	$V_I = V_+ \text{ or GND},$	See Figure 16	25°C	1.8 V		2.5		pF
Bandwidth	BW	$R_L = 50 \Omega$ , Switch ON,	See Figure 20	25°C	1.8 V		369		MHz
OFF isolation	O <sub>ISO</sub>	$R_L = 50 \Omega$ , f = 10 MHz,	Switch OFF, See Figure 21	25°C	1.8 V		-60		dB
Crosstalk	X <sub>TALK</sub>	$R_L = 50 \Omega$ , f = 10 MHz,	Switch ON, See Figure 22	25°C	1.8 V		-60		dB
Total harmonic distortion	THD	$R_L = 600 \ \Omega,$ $C_L = 50 \ pF,$	f = 20 Hz to 20 kHz, See Figure 24	25°C	1.8 V		0.4		%
Supply									
Positive supply current	l <sub>+</sub>	$V_I = V_+ \text{ or GND},$	Switch ON or OFF	25°C Full	1.95 V		0.05	0.06	μА



#### **TYPICAL PERFORMANCE**

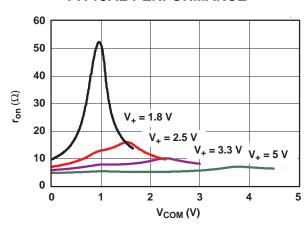


Figure 1.  $r_{on}$  vs  $V_{COM}$ 

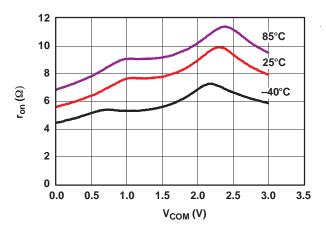


Figure 2.  $r_{on}$  vs  $V_{COM}$  ( $V_{+} = 3 V$ )

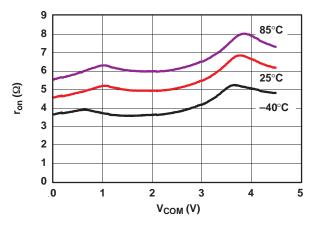


Figure 3.  $r_{on}$  vs  $V_{COM}$  ( $V_{+} = 5 V$ )



#### **TYPICAL PERFORMANCE (continued)**

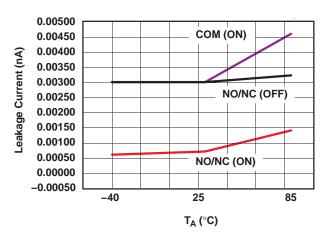


Figure 4. Leakage Current vs Temperature ( $V_{+} = 5.5 \text{ V}$ )

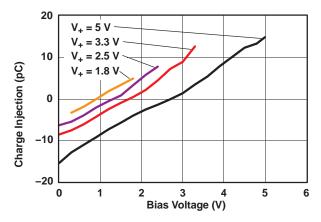


Figure 5. Charge Injection ( $Q_C$ ) vs  $V_{COM}$ 

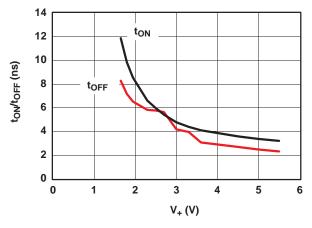


Figure 6.  $t_{ON}$  and  $t_{OFF}$  vs Supply Voltage



# **TYPICAL PERFORMANCE (continued)**

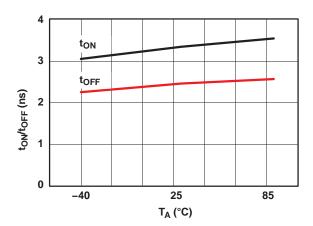


Figure 7.  $t_{ON}$  and  $t_{OFF}$  vs Temperature (V<sub>+</sub> = 5 V)

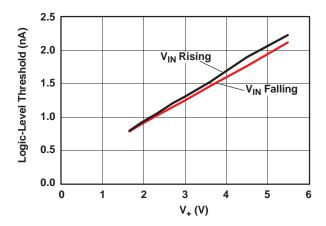


Figure 8. Logic-Level Threshold vs V<sub>+</sub>

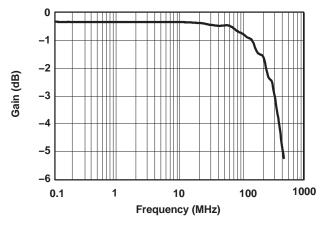


Figure 9. Bandwidth  $(V_+ = 3.3 V)$ 



# **TYPICAL PERFORMANCE (continued)**

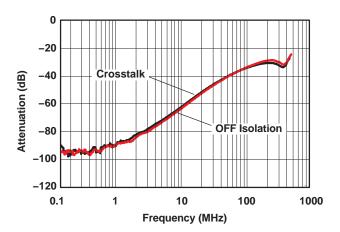


Figure 10. OFF Isolation and Crosstalk ( $V_{+} = 3.3 \text{ V}$ )

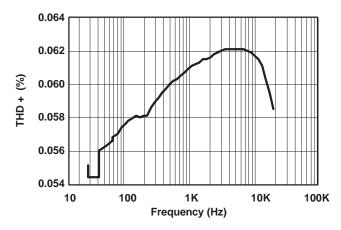


Figure 11. Total Harmonic Distortion (THD) vs Frequency ( $V_{+} = 3.3 \text{ V}$ )

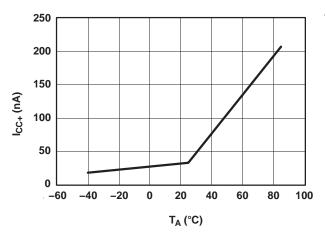


Figure 12. Power-Supply Current vs Temperature  $(V_{+} = 5 V)$ 



#### PARAMETER DESCRIPTION

SYMBOL	DESCRIPTION
V <sub>COM</sub>	Voltage at COM
$V_{NC}$	Voltage at NC
V <sub>NO</sub>	Voltage at NO
r <sub>on</sub>	Resistance between COM and NC or COM and NO ports when the channel is ON
r <sub>peak</sub>	Peak on-state resistance over a specified voltage range
Δr <sub>on</sub>	Difference of r <sub>on</sub> between channels in a specific device
r <sub>on(flat)</sub>	Difference between the maximum and minimum value of ron in a channel over the specified range of conditions
I <sub>NC(OFF)</sub>	Leakage current measured at the NC port, with the corresponding channel (NC to COM) in the OFF state
I <sub>NC(PWROFF)</sub>	Leakage current measured at the NC port during the power-down condition, $V_{+} = 0$
I <sub>NO(OFF)</sub>	Leakage current measured at the NO port, with the corresponding channel (NO to COM) in the OFF state
I <sub>NO(PWROFF)</sub>	Leakage current measured at the NO port during the power-down condition, $V_{+} = 0$
I <sub>NC(ON)</sub>	Leakage current measured at the NC port, with the corresponding channel (NC to COM) in the ON state and the output (COM) open
I <sub>NO(ON)</sub>	Leakage current measured at the NO port, with the corresponding channel (NO to COM) in the ON state and the output (COM) open
I <sub>COM(ON)</sub>	Leakage current measured at the COM port, with the corresponding channel (COM to NO or COM to NC) in the ON state and the output (NC or NO) open
I <sub>COM(PWROFF)</sub>	Leakage current measured at the COM port during the power-down condition, $V_{+} = 0$
$V_{IH}$	Minimum input voltage for logic high for the control input (IN)
$V_{IL}$	Maximum input voltage for logic low for the control input (IN)
$V_{I}$	Voltage at the control input (IN)
$I_{\rm IH},I_{\rm IL}$	Leakage current measured at the control input (IN)
t <sub>ON</sub>	Turn-on time for the switch. This parameter is measured under the specified range of conditions and by the propagation delay between the digital control (IN) signal and analog output (COM or NO) signal when the switch is turning ON.
t <sub>OFF</sub>	Turn-off time for the switch. This parameter is measured under the specified range of conditions and by the propagation delay between the digital control (IN) signal and analog output (COM or NO) signal when the switch is turning OFF.
t <sub>BBM</sub>	Break-before-make time. This parameter is measured under the specified range of conditions and by the propagation delay between the output of two adjacent analog channels (NC and NO) when the control signal changes state.
$Q_{\mathbb{C}}$	Charge injection is a measurement of unwanted signal coupling from the control (IN) input to the analog (NO or COM) output. This is measured in coulomb (C) and measured by the total charge induced due to switching of the control input. Charge injection, $Q_C = C_L \times \Delta V_{COM}$ , $C_L$ is the load capacitance and $\Delta V_{COM}$ is the change in analog output voltage.
$C_{NC(OFF)}$	Capacitance at the NC port when the corresponding channel (NC to COM) is OFF
$C_{NO(OFF)}$	Capacitance at the NO port when the corresponding channel (NO to COM) is OFF
C <sub>NC(ON)</sub>	Capacitance at the NC port when the corresponding channel (NC to COM) is ON
C <sub>NO(ON)</sub>	Capacitance at the NO port when the corresponding channel (NO to COM) is ON
C <sub>COM(ON)</sub>	Capacitance at the COM port when the corresponding channel (COM to NC or COM to NO) is ON
C <sub>I</sub>	Capacitance of control input (IN)
O <sub>ISO</sub>	OFF isolation of the switch is a measurement of OFF-state switch impedance. This is measured in dB in a specific frequency, with the corresponding channel (NC to COM or NO to COM) in the OFF state.
X <sub>TALK</sub>	Crosstalk is a measurement of unwanted signal coupling from an ON channel to an OFF channel (NC to NO or NO to NC). This is measured in a specific frequency and in dB.
BW	Bandwidth of the switch. This is the frequency in which the gain of an ON channel is -3 dB below the DC gain.
THD	Total harmonic distortion is defined as the ratio of the root mean square (RMS) value of the second, third, and higher harmonics to the magnitude of fundamental harmonic.
l <sub>+</sub>	Static power-supply current with the control (IN) pin at V <sub>+</sub> or GND
V <sub>OUTU</sub>	Output voltage during an undershoot event. This is measured by turning off a specific channel and applying an undershoot voltage at the input of the switch.
V <sub>OUTO</sub>	Output voltage during an overshoot event. This is measured by turning off a specific channel and applying an overshoot voltage at the input of the switch.



#### PARAMETER MEASUREMENT INFORMATION

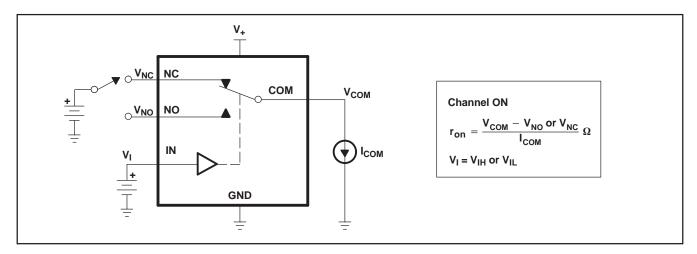


Figure 13. ON-State Resistance (r<sub>on</sub>)

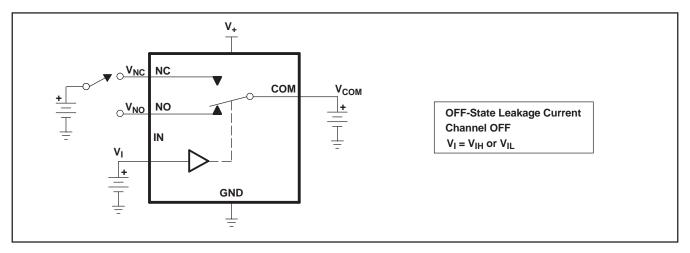


Figure 14. OFF-State Leakage Current ( $I_{NC(OFF)}$ ,  $I_{NC(PWROFF)}$ ,  $I_{NO(OFF)}$ ,  $I_{NO(PWROFF)}$ ,  $I_{COM(PWROFF)}$ )



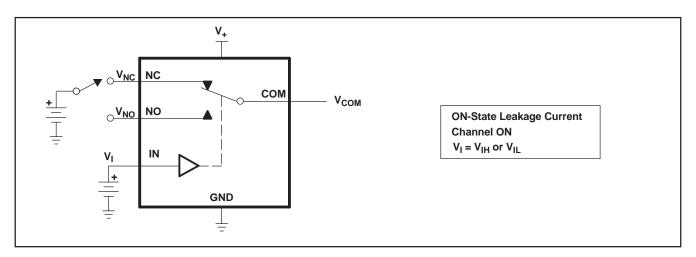


Figure 15. ON-State Leakage Current ( $I_{COM(ON)}$ ,  $I_{NC(ON)}$ ,  $I_{NO(ON)}$ )

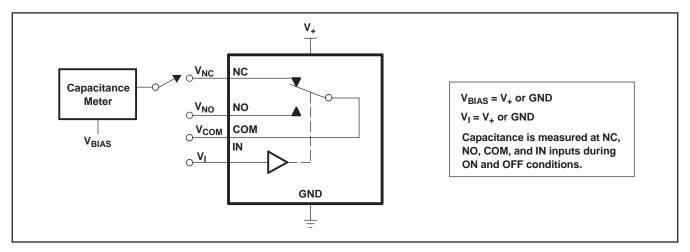
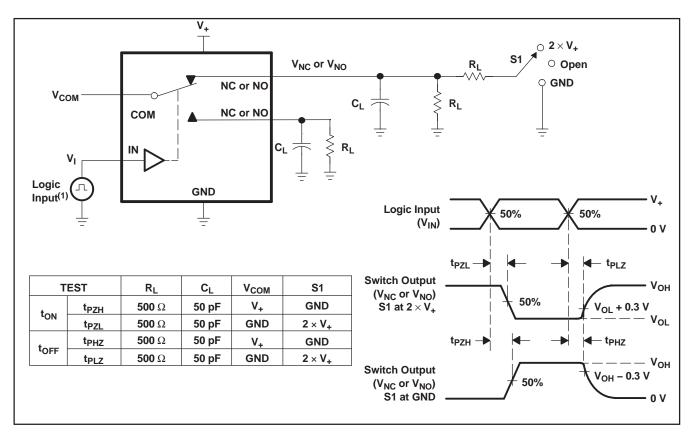


Figure 16. Capacitance ( $C_{IN}$ ,  $C_{COM(ON)}$ ,  $C_{NC(OFF)}$ ,  $C_{NO(OFF)}$ ,  $C_{NC(ON)}$ ,  $C_{NO(ON)}$ )





(1) All input pulses are supplied by generators having the following characteristics: PRR  $\leq$  10 MHz,  $Z_O = 50 \Omega$ ,  $t_r < 5 \text{ ns}$ ,  $t_f < 5 \text{ ns}$ .

Figure 17. Turn-On (t<sub>ON</sub>) and Turn-Off (t<sub>OFF</sub>) Time



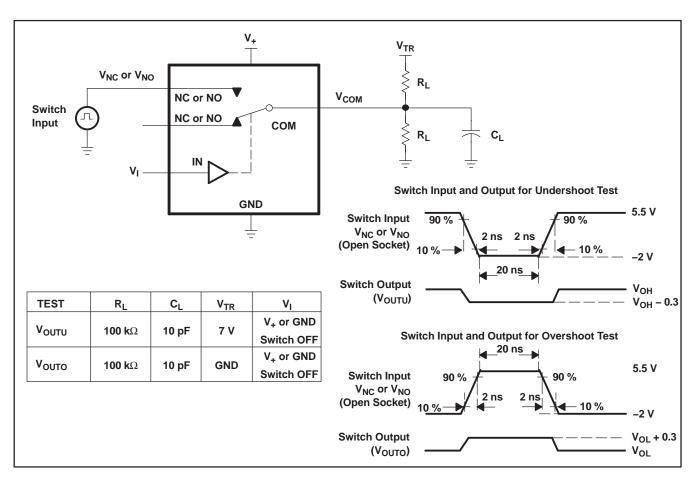
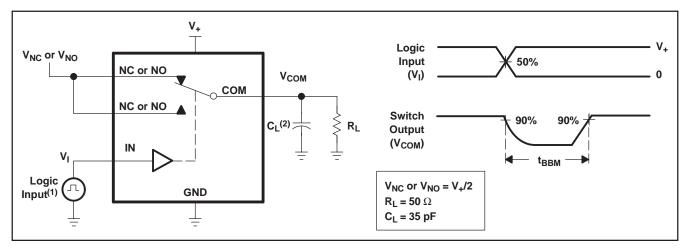


Figure 18. Undershoot and Overshoot Test



- (1) All input pulses are supplied by generators having the following characteristics: PRR  $\leq$  10 MHz,  $Z_O = 50 \Omega$ ,  $t_r < 5 \text{ ns}$ ,  $t_f < 5 \text{ ns}$ .
- (2) C<sub>L</sub> includes probe and jig capacitance.

Figure 19. Break-Before-Make (t<sub>BBM</sub>) Time



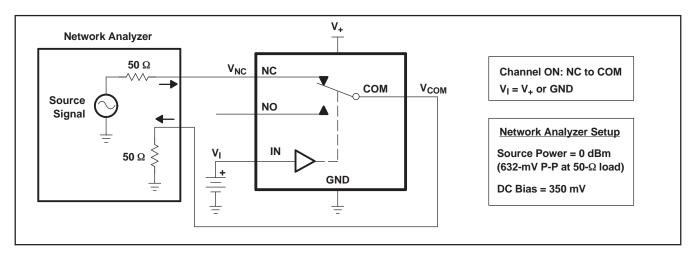


Figure 20. Bandwidth (BW)

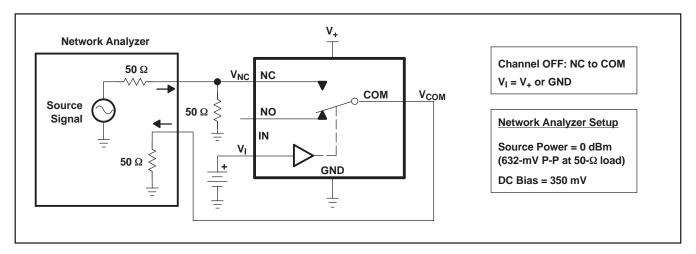


Figure 21. OFF Isolation (O<sub>ISO</sub>)

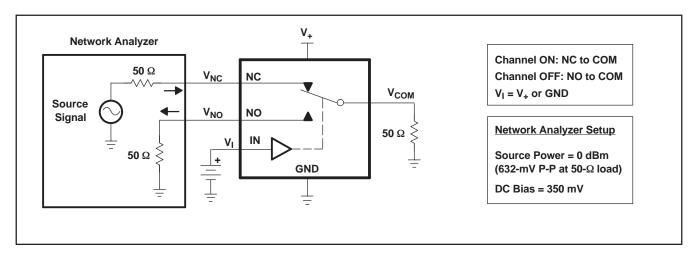
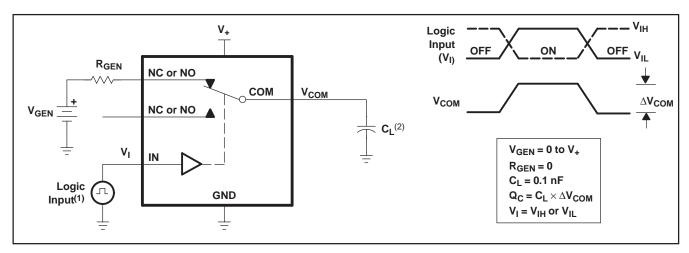


Figure 22. Crosstalk (X<sub>TALK</sub>)

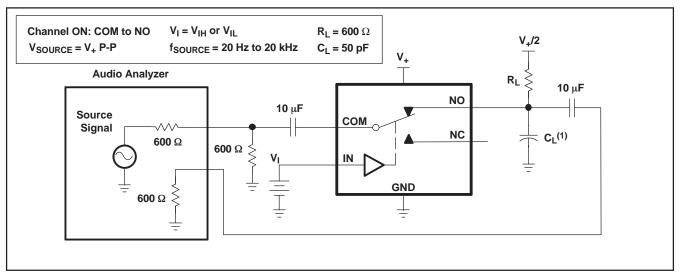
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- (1) All input pulses are supplied by generators having the following characteristics: PRR  $\leq$  10 MHz,  $Z_O = 50 \Omega$ ,  $t_r < 5 \text{ ns}$ ,  $t_f < 5 \text{ ns}$ .
- (2) C<sub>L</sub> includes probe and jig capacitance.

Figure 23. Charge Injection (Q<sub>C</sub>)



(1) C<sub>L</sub> includes probe and jig capacitance.

Figure 24. Total Harmonic Distortion (THD)





26-Mar-2013

#### PACKAGING INFORMATION

Orderable Device	Status	Package Type	Package Drawing		Package Qty	Eco Plan	Lead/Ball Finish	MSL Peak Temp	Op Temp (°C)	Top-Side Markings	Samples
TS5A63157DBVR	ACTIVE	SOT-23	DBV	6	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	(JBEF ~ JBER)	Samples
TS5A63157DBVRE4	ACTIVE	SOT-23	DBV	6	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	(JBEF ~ JBER)	Samples
TS5A63157DBVRG4	ACTIVE	SOT-23	DBV	6	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	(JBEF ~ JBER)	Samples
TS5A63157DCKR	ACTIVE	SC70	DCK	6	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	(J75 ~ J7F ~ J7R)	Samples
TS5A63157DCKRE4	ACTIVE	SC70	DCK	6	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	(J75 ~ J7F ~ J7R)	Samples
TS5A63157DCKRG4	ACTIVE	SC70	DCK	6	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	(J75 ~ J7F ~ J7R)	Samples

(1) The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

**TBD:** The Pb-Free/Green conversion plan has not been defined.

**Pb-Free** (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes. **Pb-Free** (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between

the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

<sup>(4)</sup> Multiple Top-Side Markings will be inside parentheses. Only one Top-Side Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Top-Side Marking for that device.



### PACKAGE OPTION ADDENDUM

26-Mar-2013

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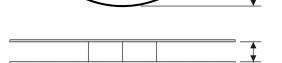
# PACKAGE MATERIALS INFORMATION

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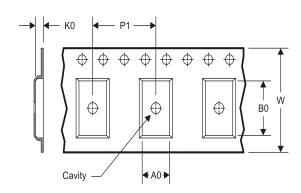
#### TAPE AND REEL INFORMATION

#### **REEL DIMENSIONS**





#### **TAPE DIMENSIONS**



A0	Dimension designed to accommodate the component width
В0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

#### TAPE AND REEL INFORMATION

\*All dimensions are nominal

All dimensions are nominal												
Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
TS5A63157DBVR	SOT-23	DBV	6	3000	180.0	8.4	3.23	3.17	1.37	4.0	8.0	Q3
TS5A63157DBVR	SOT-23	DBV	6	3000	178.0	9.0	3.23	3.17	1.37	4.0	8.0	Q3
TS5A63157DCKR	SC70	DCK	6	3000	178.0	9.0	2.4	2.5	1.2	4.0	8.0	Q3
TS5A63157DCKR	SC70	DCK	6	3000	178.0	9.2	2.4	2.4	1.22	4.0	8.0	Q3

**PACKAGE MATERIALS INFORMATION** 

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\*All dimensions are nominal

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Device	Device Package Type		Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
TS5A63157DBVR	SOT-23	DBV	6	3000	202.0	201.0	28.0
TS5A63157DBVR	SOT-23	DBV	6	3000	180.0	180.0	18.0
TS5A63157DCKR	SC70	DCK	6	3000	180.0	180.0	18.0
TS5A63157DCKR	SC70	DCK	6	3000	180.0	180.0	18.0

# DBV (R-PDSO-G6)

# PLASTIC SMALL-OUTLINE PACKAGE



NOTES:

- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion. Mold flash and protrusion shall not exceed 0.15 per side.
- D. Leads 1,2,3 may be wider than leads 4,5,6 for package orientation.
- Falls within JEDEC MO-178 Variation AB, except minimum lead width.



# DBV (R-PDSO-G6)

# PLASTIC SMALL OUTLINE



NOTES:

- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Customers should place a note on the circuit board fabrication drawing not to alter the center solder mask defined pad.
- D. Publication IPC-7351 is recommended for alternate designs.
- E. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Example stencil design based on a 50% volumetric metal load solder paste. Refer to IPC-7525 for other stencil recommendations.



# DCK (R-PDSO-G6)

# PLASTIC SMALL-OUTLINE PACKAGE



NOTES: A. All linear dimensions are in millimeters.

- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion. Mold flash and protrusion shall not exceed 0.15 per side.
- D. Falls within JEDEC MO-203 variation AB.



# DCK (R-PDSO-G6)

# PLASTIC SMALL OUTLINE



NOTES:

- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Customers should place a note on the circuit board fabrication drawing not to alter the center solder mask defined pad.
- D. Publication IPC-7351 is recommended for alternate designs.
- E. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Example stencil design based on a 50% volumetric metal load solder paste. Refer to IPC-7525 for other stencil recommendations.



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